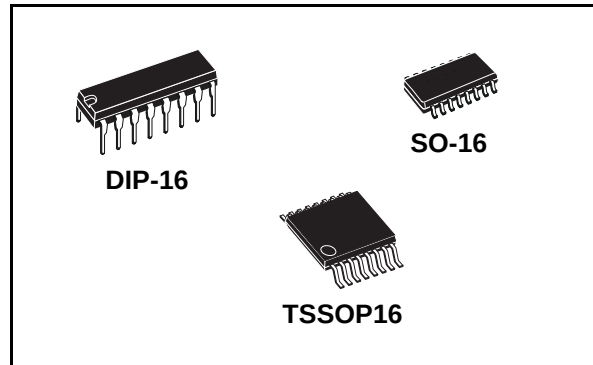


8-bit PISO shift register

Features

- High speed:
 - $t_{PD} = 15 \text{ ns}$ (typ.) at $V_{CC} = 6 \text{ V}$
- Low power dissipation:
 - $I_{CC} = 4 \mu\text{A}$ (max.) at $T_A = 25 \text{ }^\circ\text{C}$
- High noise immunity:
 - $V_{NIH} = V_{NIL} = 28 \% V_{CC}$ (Min.)
- Symmetrical output impedance:
 - $|I_{OH}| = I_{OL} = 4 \text{ mA}$ (min)
- Balanced propagation delays:
 - $t_{PLH} \cong t_{PHL}$
- Wide operating voltage range:
 - $V_{CC} (\text{opr}) = 2 \text{ V to } 6 \text{ V}$
- Pin and function compatible with 74 series 165



Description

The M74HC165 is a high speed CMOS 8-bit PISO (parallel-in-serial-out) shift register fabricated with silicon gate C²MOS technology. This device contains eight clocked master slave RS flip-flops connected as a shift register, with auxiliary gating to provide overriding asynchronous parallel entry. The parallel data enter when the shift/load input is low and can change while shift/load is low, provided that the recommended set-up and hold times are observed. For clocked operation, shift/load must be high. The two clock inputs perform identically: one can be used as a clock inhibit by applying a high signal, to allow this operation clocking is accomplished through a 2-input nor gate. To avoid double clocking, however, the inhibit signal should only go high while the clock is high. Otherwise the rising inhibit signal causes the same response as rising clock edge. All inputs are equipped with protection circuits against static discharge and transient excess voltage.

Table 1. Device summary

Order code	Package	Packaging
M74HC165B1R	DIP-16	Tube
M74HC165RM13TR	SO-16	Tape and reel
M74HC165TTR	TSSOP16	Tape and reel

Contents

1	Logic symbols and I/O equivalent circuit	3
2	Pin settings	4
2.1	Pin connection	4
2.2	Pin description	4
3	Logic states	5
3.1	Truth table	5
3.2	Logic diagram	5
3.3	Timing chart	6
4	Maximum rating	7
4.1	Recommended operating conditions	7
5	Electrical characteristics	8
6	Test circuit	11
7	Waveforms	12
8	Package mechanical data	14
9	Revision history	17

1 Logic symbols and I/O equivalent circuit

Figure 1. IEC logic symbols

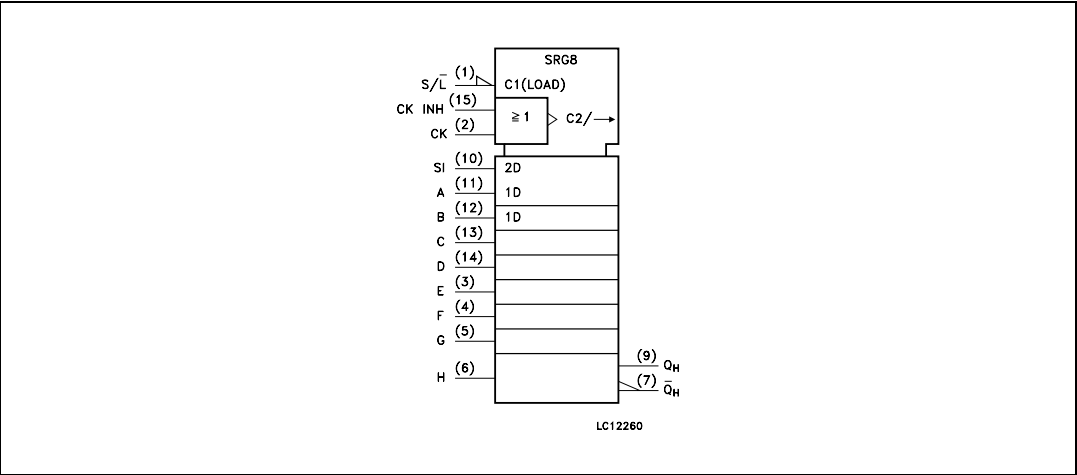
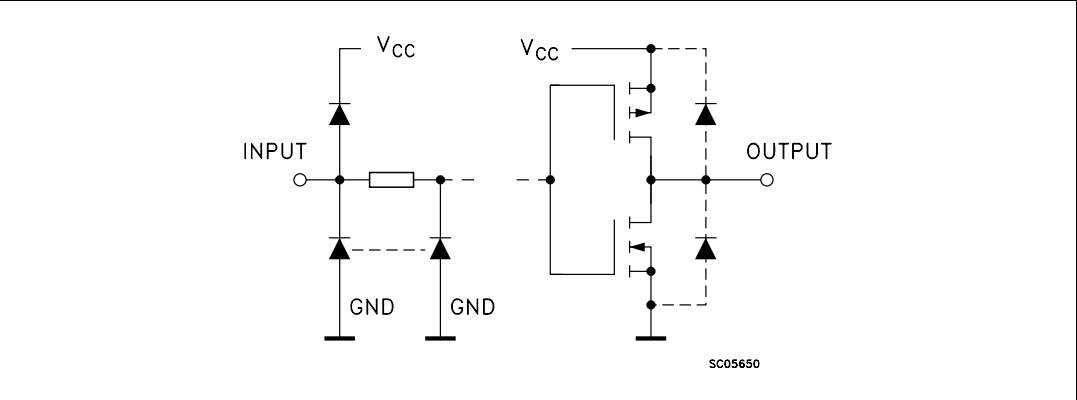


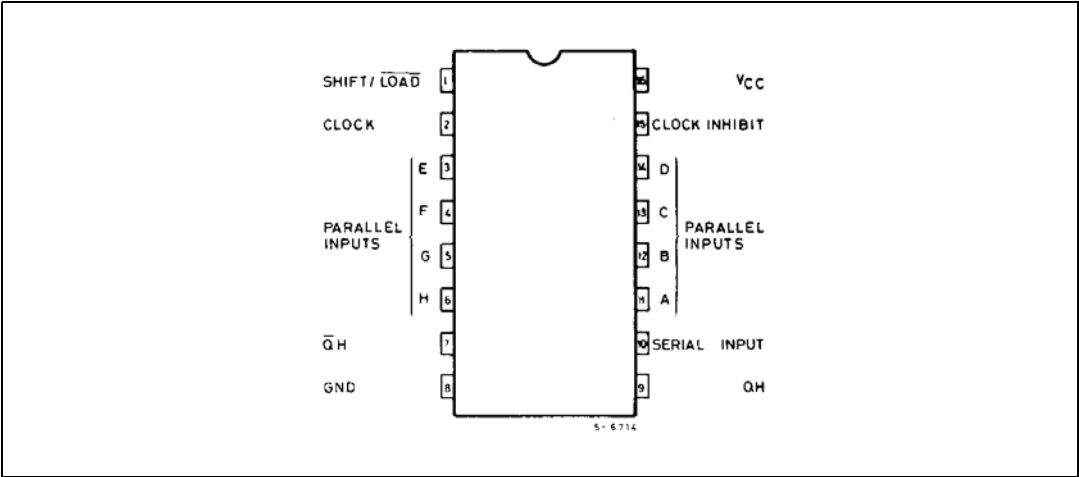
Figure 2. Input and output equivalent circuit



2 Pin settings

2.1 Pin connection

Figure 3. Pin connection (top through view)



2.2 Pin description

Table 2. Pin description

Pin number	Symbol	Name and function
1	SHIFT/LOAD	Data inputs
2	CLOCK	Clock input (low to high, edge triggered)
7	$\overline{QH}$	Complementary output
9	QH	Serial output
10	SI	Serial input
11, 12, 13, 14, 3, 4, 5, 6	A to H	Parallel data inputs
15	CLOCK INH	Clock inhibit
8	GND	Ground (0 V)
16	V _{CC}	Positive supply voltage

3 Logic states

3.1 Truth table

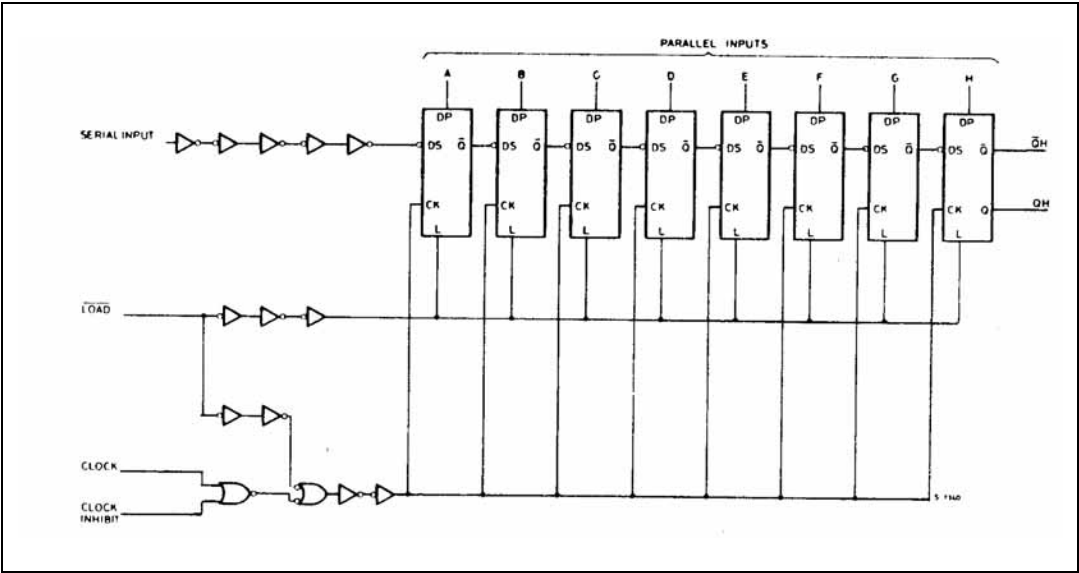
Table 3. Truth table

Inputs					Internal outputs		Outputs
Shift /Load	Clock INH	Clock	SI	A.....H	QA	QB	QH
L	X	X	X	a.....h	a	b	h
H	L		H	X	H	QAn	QGn
H	L		L	X	L	QAn	QGn
H		L	H	X	H	QAn	QGn
H		L	L	X	L	QAn	QGn
H	X	H	X	X	No change		
H	H	X	X	X	No change		

Note: a.....h : the level of steady input voltage at inputs a through respectively QAn - QGn : the level of QA - QG, respectively. Before the most recent transition of the clock.

3.2 Logic diagram

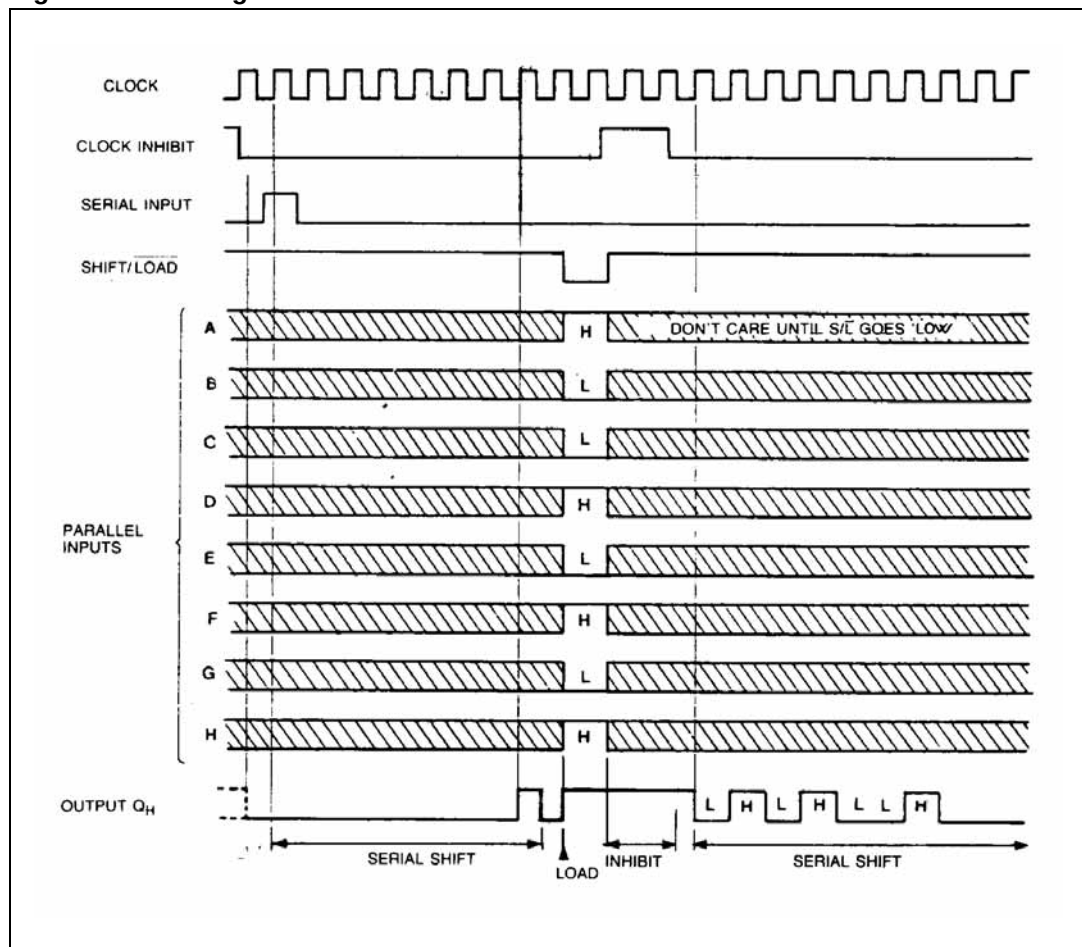
Figure 4. Logic diagram



Note: This logic diagram has not to be used to estimate propagation delays

3.3 Timing chart

Figure 5. Timing chart



4 Maximum rating

Stressing the device above the rating listed in the “absolute maximum ratings” table may cause permanent damage to the device. these are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. exposure to absolute maximum rating conditions for extended periods may affect device reliability. refer also to the STMicroelectronics sure program and other relevant quality documents.

Table 4. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{CC}	Supply voltage	-0.5 to +7	V
V_I	DC input voltage	-0.5 to $V_{CC} + 0.5$	V
V_O	DC output voltage	-0.5 to $V_{CC} + 0.5$	V
I_{IK}	DC input diode current	± 20	mA
I_{OK}	DC output diode current	± 20	mA
I_O	DC output current	± 25	mA
I_{CC} or I_{GND}	DC V_{CC} or ground current	± 50	mA
P_D	Power dissipation	500 ⁽¹⁾	mW
T_{stg}	Storage temperature	-65 to +150	°C
T_L	Lead temperature (10 sec)	300	°C

1. (*) 500 mW at 65 °C; derate to 300 mW by 10 mW/°C from 65°C to 85°C

4.1 Recommended operating conditions

Table 5. Recommended operating conditions

Symbols	Parameter		Value	Unit
V _{CC}	Supply voltage		2 to 6	V
V _I	Input voltage		0 to V _{CC}	V
V _O	Output voltage		0 to V _{CC}	V
T _{op}	Operating temperature		-55 to 125	°C
t _r , t _f	Input rise and fall time	V _{CC} = 2.0 V	0 to 1000	ns
		V _{CC} = 4.5 V	0 to 500	ns
		V _{CC} = 6.0 V	0 to 400	ns

5 Electrical characteristics

Table 6. DC specifications

Symbol	Parameter	Test condition		Value								Unit
		V _{CC} (V)		T _A = 25°C			-40 to 85°C		-55 to 125°C			
				Min	Typ	Max	Min	Max	Min	Max		
V _{IH}	High level input voltage	2.0		1.5			1.5		1.5		V	
		4.5		3.15			3.15		3.15			
		6.0		4.2			4.2		4.2			
V _{IL}	Low level input voltage	2.0				0.5		0.5		0.5	V	
		4.5				1.35		1.35		1.35		
		6.0				1.8		1.8		1.8		
V _{OH}	High level output voltage	2.0	I _O = -20 μA	1.9	2.0		1.9		1.9		V	
		4.5	I _O = -20 μA	4.4	4.5		4.4		4.4			
		6.0	I _O = -20 μA	5.9	6.0		5.9		5.9			
		4.5	I _O = -4.0 mA	4.18	4.31		4.13		4.10			
		6.0	I _O = -5.2 mA	5.68	5.8		5.63		5.60			
V _{OL}	Low level output voltage	2.0	I _O = 20 μA		0.0	0.1		0.1		0.1	V	
		4.5	I _O = 20 μA		0.0	0.1		0.1		0.1		
		6.0	I _O = 20 μA		0.0	0.1		0.1		0.1		
		4.5	I _O = 4.0 mA		0.17	0.26		0.33		0.40		
		6.0	I _O = 5.2 mA		0.18	0.26		0.33		0.40		
I _I	Input leakage current	6.0	V _I = V _{CC} or GND			±0.1		±1		±1	μA	
I _{CC}	Quiescent supply current	6.0	V _I = V _{CC} or GND			4		40		80	μA	

Table 7. AC electrical characteristics ($C_L = 50$ pF, Input $t_r = t_f = 6$ ns)

Symbol	Parameter	Test condition		Value							Unit
		V _{CC} (V)		T _A = 25°C			-40 to 85°C		-55 to 125°C		
				Min	Typ	Max	Min	Max	Min	Max	
t _{TLH} t _{THL}	Output transition time	2.0			30	75		95		110	ns
		4.5			8	15		19		22	
		6.0			7	13		16		19	
t _{PLH} t _{PHL}	Propagation delay time (CLOCK - QH, $\overline{QH}$)	2.0			55	150		190		225	ns
		4.5			18	30		38		45	
		6.0			15	26		33		38	
t _{PLH} t _{PHL}	Propagation delay time (SHIFT/ $\overline{LOAD}$ - QH, $\overline{QH}$)	2.0			65	165		205	250		ns
		4.5			21	33		41		50	
		6.0			18	28		35		43	
t _{PLH} t _{PHL}	Propagation delay time (H - QH, $\overline{QH}$)	2.0			52	135		170		205	ns
		4.5			17	27		34		41	
		6.0			14	23		29		35	
fMAX	Maximum clock frequency	2.0		7.4	15		6.0		4.8		MHz
		4.5		37	60		30		24		
		6.0		44	71		35		28		
t _{W(H)} t _{W(L)}	Minimum pulse width (CLOCK)	2.0			24	75		95		110	ns
		4.5			6	15		19		22	
		6.0			5	13		16		19	
t _{W(L)}	Minimum pulse width (SHIFT/ $\overline{LOAD}$)	2.0			32	75		95		110	ns
		4.5			8	15		19		22	
		6.0			7	13		16		19	
t _s	Minimum set-up time (PI - SHIFT/ $\overline{LOAD}$) (SI - CLOCK) (SHIFT/ $\overline{LOAD}$ - CK)	2.0			24	75		95		110	ns
		4.5			6	15		19		22	
		6.0			5	13		16		19	
t _h	Minimum hold time (PI - SHIFT/ $\overline{LOAD}$) (SI - CLOCK) (SHIFT/ $\overline{LOAD}$ - CK)	2.0				0		0		0	ns
		4.5				0		0		0	
		6.0				0		0		0	
t _{REM}	Minimum removal time (CLOCK - CK INH)	2.0			20	75		95		110	ns
		4.5			5	15		19		22	
		6.0			4	13		16		19	

Table 8. Capacitive characteristics

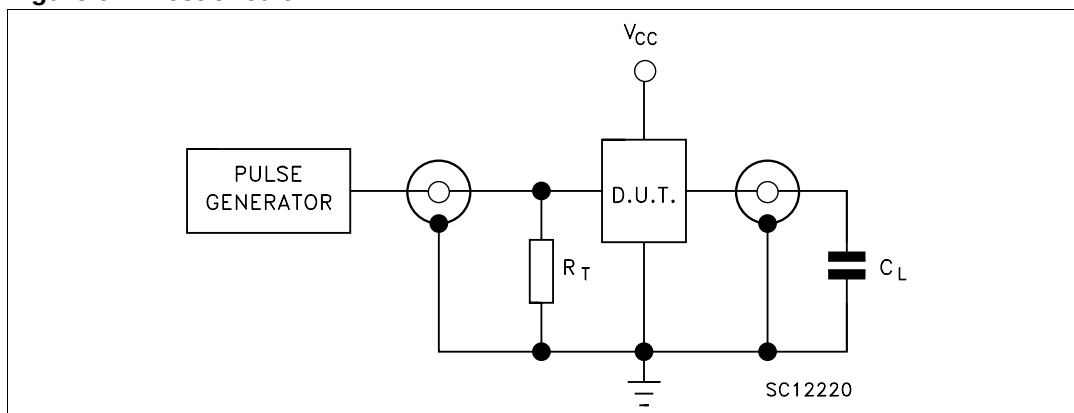
Symbol	Parameter	Test condition		Value						Unit	
		V _{CC} (V)		T _A = 25 °C			-40 to 85 °C		-55 to 125 °C		
				Min	Typ	Max	Min	Max	Min		Max
C _{IN}	Input capacitance	5.0			5	10		10		10	pF
C _{PD}	Power dissipation capacitance ⁽¹⁾	5.0			55						pF

1. C_{PD} is defined as the value of the IC's internal equivalent capacitance which is calculated from the operating current consumption without load. (Refer to Test Circuit). Average operating current can be obtained by the following equation.

$$I_{CC(opr)} = C_{PD} \times V_{CC} \times f_{IN} + I_{CC}$$

6 Test circuit

Figure 6. Test circuit



$C_L = 50 \text{ pF}$ or equivalent (includes jig and probe capacitance)

$R_T = Z_{OUT}$ of pulse generator (typically 50Ω)

7 Waveforms

Figure 7. Serial mode propagation delay ($f = 1\text{ MHz}$; 50% duty cycle)

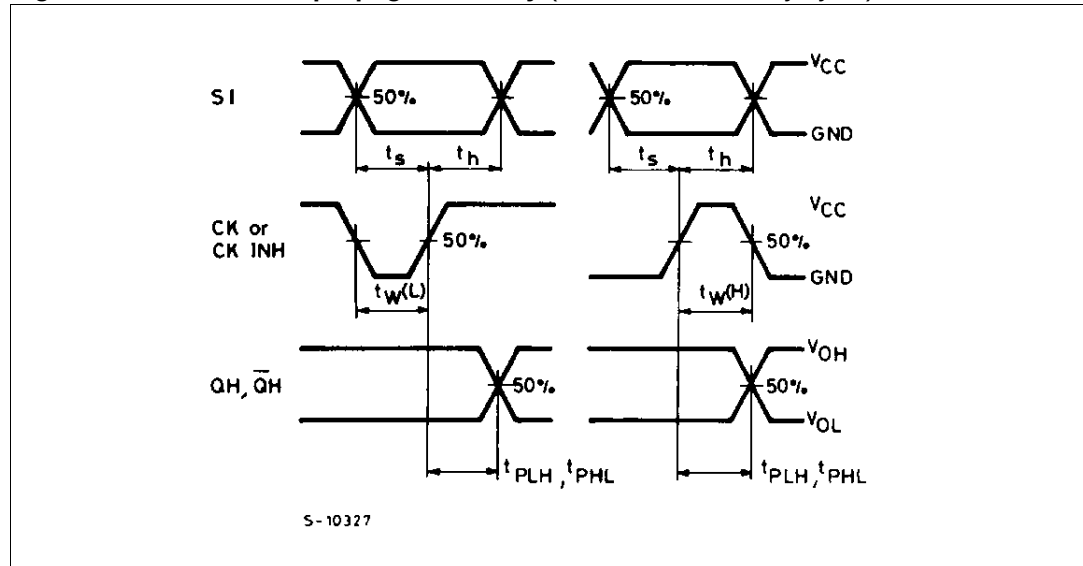


Figure 8. Parallel mode propagation delay ($f = 1\text{ MHz}$; 50% duty cycle)

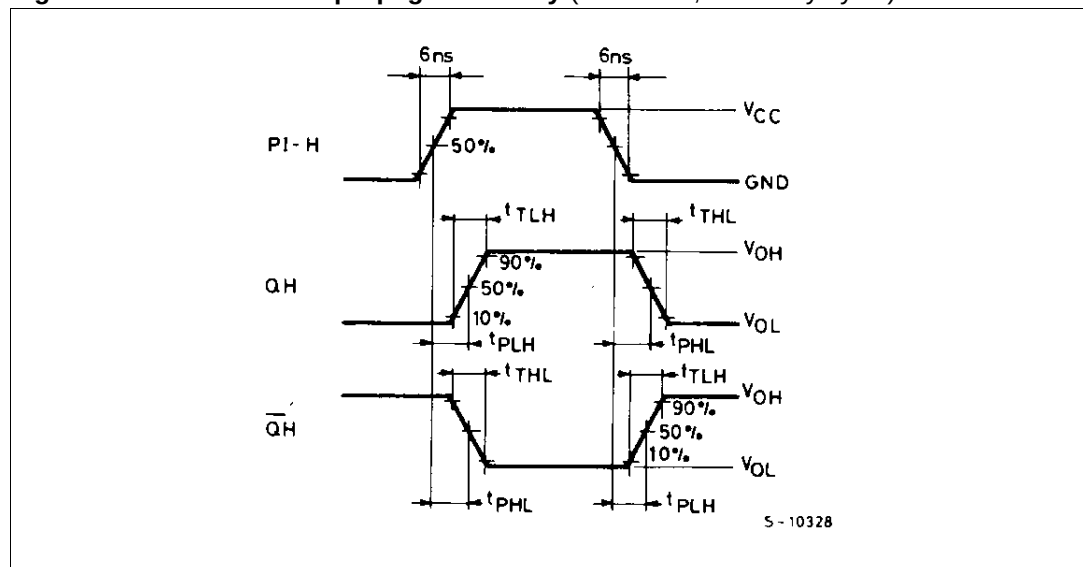


Figure 9. Minimum pulse width ($S/\bar{L}$), propagation delay times
($f = 1\text{ MHz}$; 50% duty cycle)

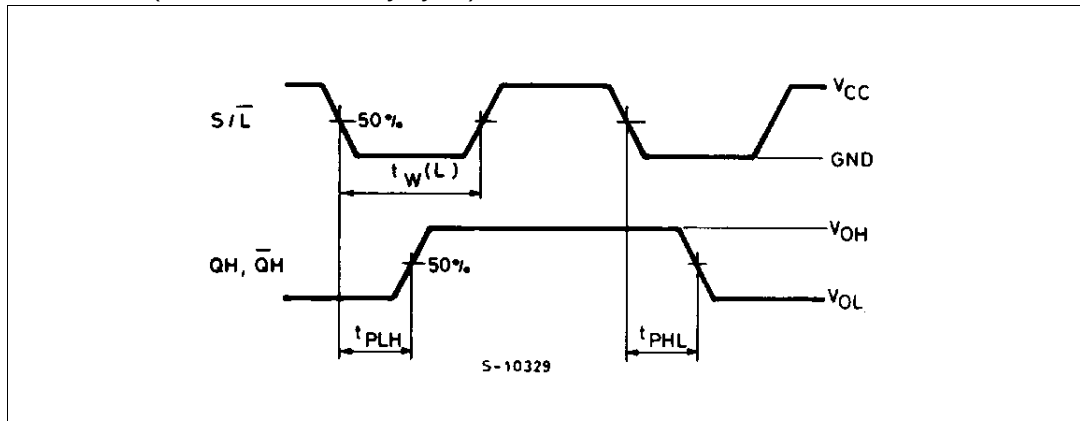


Figure 10. Setup and hold time (PI to $S/\bar{L}$) ($f = 1\text{ MHz}$; 50% duty cycle)

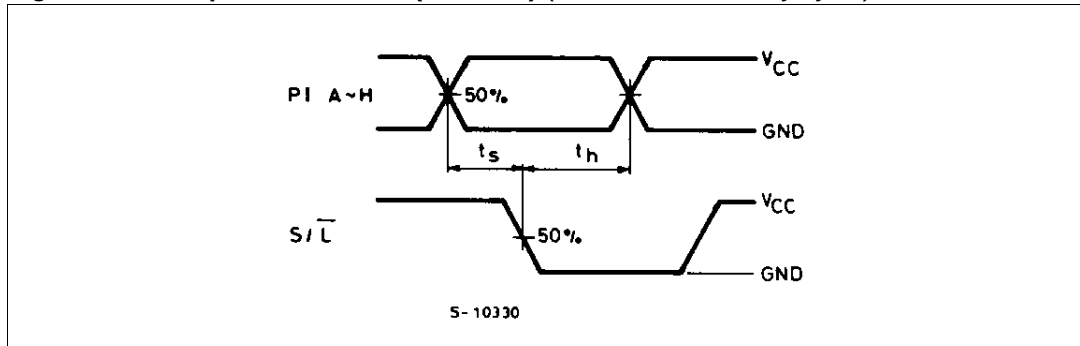
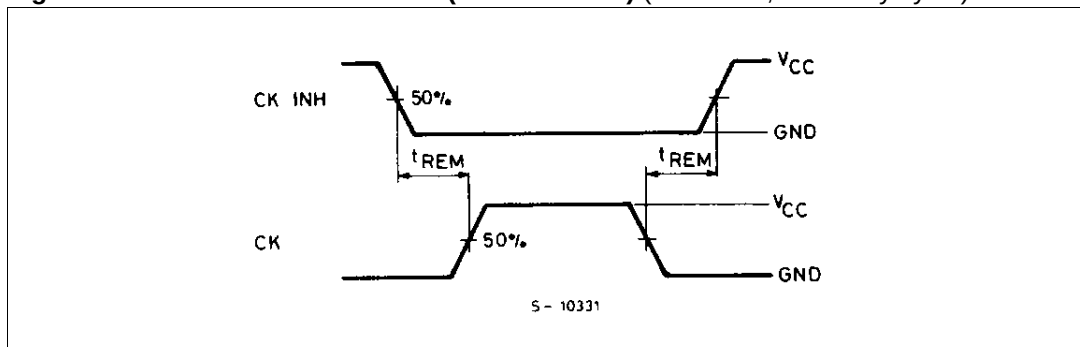


Figure 11. Minimum removal time (CK INH to CK) ($f = 1\text{ MHz}$; 50% duty cycle)



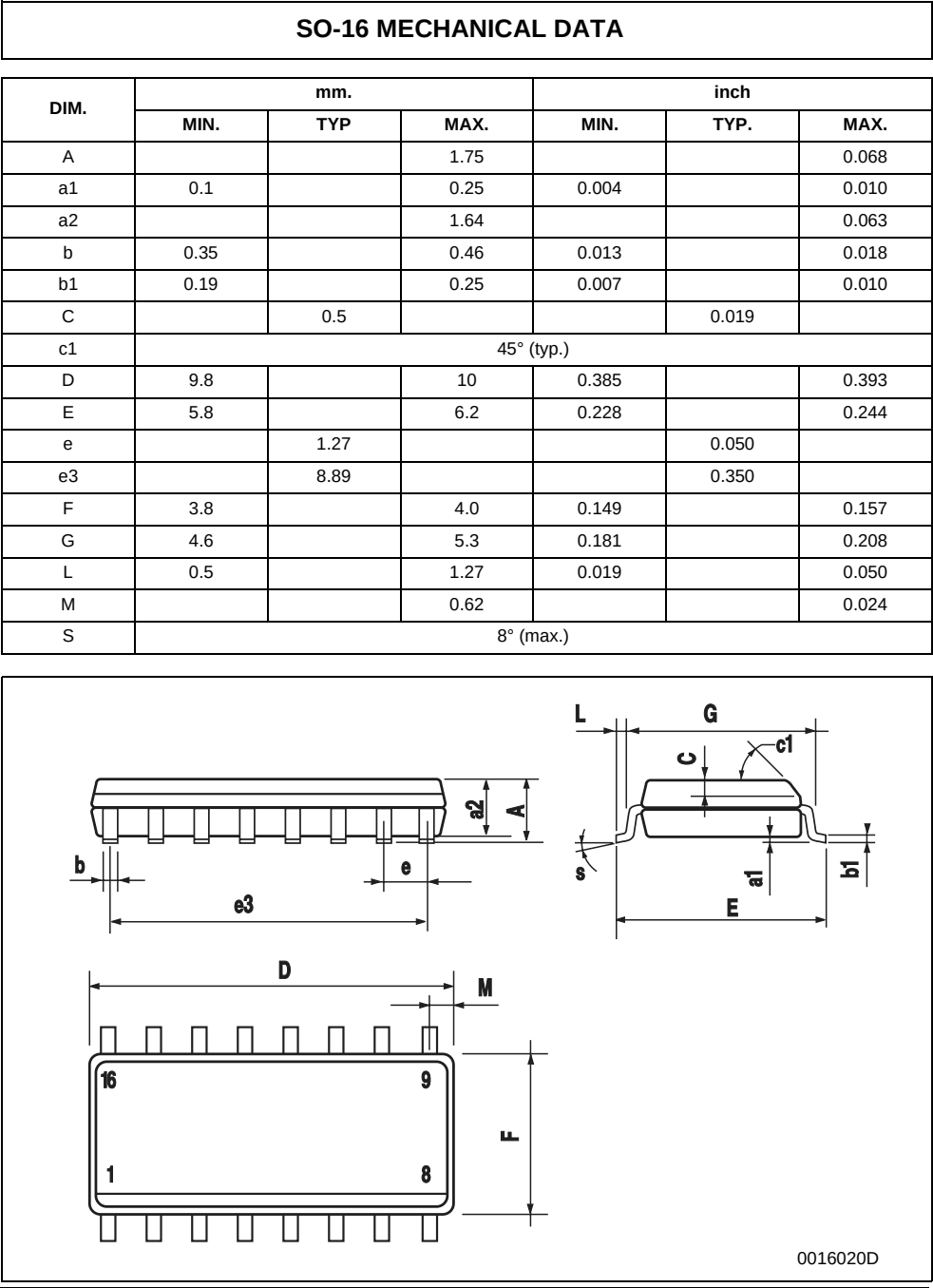
8 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK[®] packages. These packages have a Lead-free second level interconnect . The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

Plastic DIP-16 (0.25) MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
a1	0.51			0.020		
B	0.77		1.65	0.030		0.065
b		0.5			0.020	
b1		0.25			0.010	
D			20			0.787
E		8.5			0.335	
e		2.54			0.100	
e3		17.78			0.700	
F			7.1			0.280
I			5.1			0.201
L		3.3			0.130	
Z			1.27			0.050

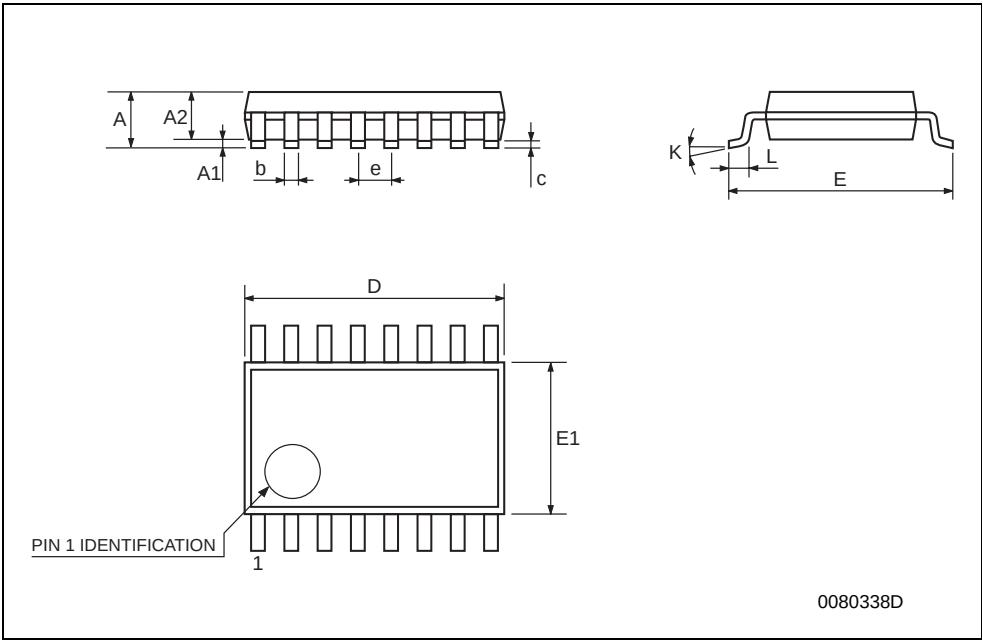
The diagram illustrates the mechanical specifications of the M74HC165 Plastic DIP-16 package. It includes three views: a top view, a side view, and a pin 1 indicator view. The top view shows the package body with dimensions D (total width), E (body width), and L (body length). Pin 1 is indicated by a notch on the left side. The side view shows the package height with dimensions a1 (pin height), L (package height), and b1 (pin thickness). The pin 1 indicator view shows the package width with dimensions Z (pin thickness), b (pin width), B (pin pitch), e (pin spacing), and e3 (total pin width). The pin numbers 1, 8, 9, and 16 are also indicated on the top view.

P001C



TSSOP16 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			1.2			0.047
A1	0.05		0.15	0.002	0.004	0.006
A2	0.8	1	1.05	0.031	0.039	0.041
b	0.19		0.30	0.007		0.012
c	0.09		0.20	0.004		0.0079
D	4.9	5	5.1	0.193	0.197	0.201
E	6.2	6.4	6.6	0.244	0.252	0.260
E1	4.3	4.4	4.48	0.169	0.173	0.176
e		0.65 BSC			0.0256 BSC	
K	0°		8°	0°		8°
L	0.45	0.60	0.75	0.018	0.024	0.030

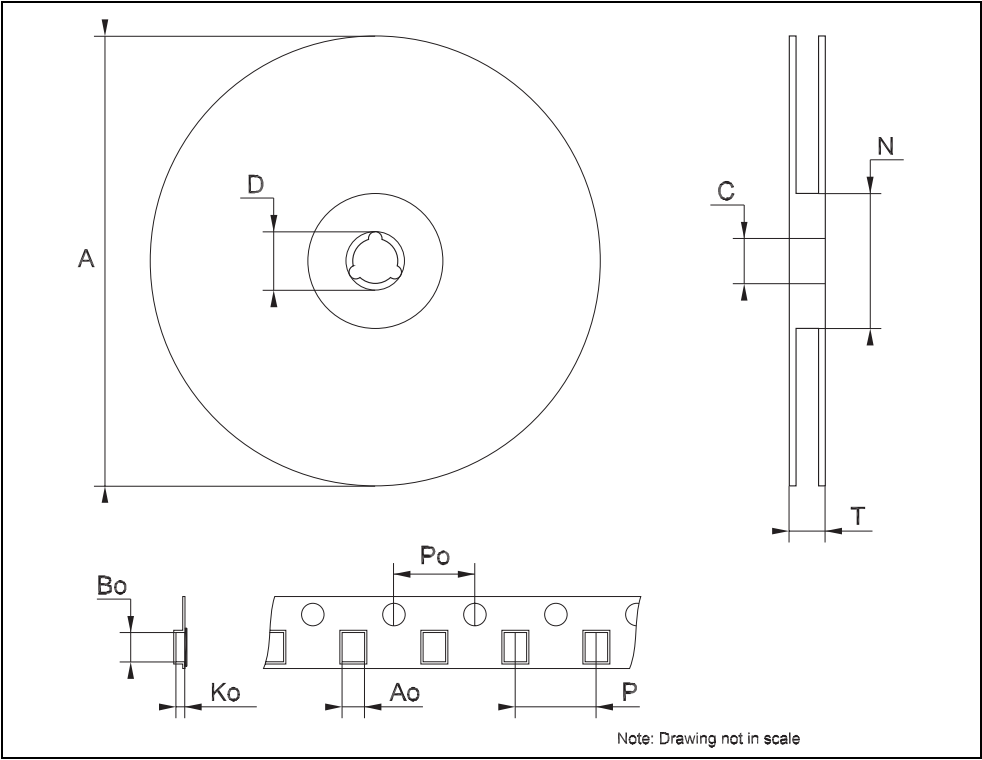


Tape & Reel SO-16 MECHANICAL DATA						
DIM.	mm.			inch		
	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
A			330			12.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			22.4			0.882
Ao	6.45		6.65	0.254		0.262
Bo	10.3		10.5	0.406		0.414
Ko	2.1		2.3	0.082		0.090
Po	3.9		4.1	0.153		0.161
P	7.9		8.1	0.311		0.319

The diagram illustrates the mechanical specifications of the M74HC165 package. It includes three views: a top view showing the circular package body with diameter A and a central feature with diameter D; a side view showing the package height N and lead thickness T, with a lead width C; and a detail view of the lead profile showing dimensions Bo (lead width), Ko (lead thickness), Ao (lead pitch), Po (lead spacing), and P (lead length). A note at the bottom right states: 'Note: Drawing not in scale'.

Tape & Reel SSOP16 MECHANICAL DATA

DIM.	mm.			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			330			12.992
C	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
T			22.4			0.882
Ao	8.4		8.6	0.331		0.339
Bo	6.7		6.9	0.264		0.272
Ko	2.9		3.1	0.114		0.122
Po	3.9		4.1	0.153		0.161
P	11.9		12.1	0.468		0.476



9 Revision history

Table 9. Document revision history

Date	Revision	Changes
9-Jul-2001	3	Final release.
21-Mar-2007	4	The document has been reformatted, updated Table 2: Pin description on page 4
26-May-2008	5	Removed: M74HC165M1R order code. Minor changes in the text. Added: SO-16 and TSSOP16 tape and reel specifications.

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

UNLESS EXPRESSLY APPROVED IN WRITING BY AN AUTHORIZED ST REPRESENTATIVE, ST PRODUCTS ARE NOT RECOMMENDED, AUTHORIZED OR WARRANTED FOR USE IN MILITARY, AIR CRAFT, SPACE, LIFE SAVING, OR LIFE SUSTAINING APPLICATIONS, NOR IN PRODUCTS OR SYSTEMS WHERE FAILURE OR MALFUNCTION MAY RESULT IN PERSONAL INJURY, DEATH, OR SEVERE PROPERTY OR ENVIRONMENTAL DAMAGE. ST PRODUCTS WHICH ARE NOT SPECIFIED AS "AUTOMOTIVE GRADE" MAY ONLY BE USED IN AUTOMOTIVE APPLICATIONS AT USER'S OWN RISK.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2008 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com

